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10/586,598	07/20/2006	Tadashi Maeda	2006_1151A	1659
513	7590	07/15/2011		
WENDEROTH, LIND & PONACK, L.L.P.			EXAMINER	
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Suite 400 East				
Washington, DC 20005-1503			ART UNIT	PAPER NUMBER
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Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Notice of the Office communication was sent electronically on above-indicated "Notification Date" to the following e-mail address(es):

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Request for Reconsideration

1. The request for reconsideration has been considered but does NOT place the application in condition for allowance because:
2. Applicant argues that the Examiner is inconsistent in referring to the modification of Mei in view of Kang. However, as stated in the remarks, the Examiner never suggested a modification of Mei's solder **composition**, only the **shape** of the metal powders. This is not inconsistent with either statement: the composition has not been modified, but the flake-shaped powders have been included in the combination.
3. Applicant next argues that Mei's solder composition does not meet the limitations of the claim because after melting, there are no particles left in the solder. However, this is incorrect because the solder must re-solidify. It does not stay in a liquid state forever. The solder is melted and then cooled to become solid again after the reflow process. Therefore, in the resolidification process, the metal particles nucleate and grow until all of the solder has been solidified. Therefore, after the solidification process, the particles in the solder have returned. Furthermore, please note that the claim as written does not require the scales to be in the solder composition after the reflow process, only before.
4. For these reasons, all previous rejections, including the double patenting, have been maintained.

/Megha Mehta/
Examiner, Art Unit 1783

/David R. Sample/
Supervisory Patent Examiner, Art Unit 1783